2A, 20V - 40V Schottky Barrier Surface Mount Rectifier

FEATURES

- Low power loss, high efficiency
- Ideal for automated placement
- Guard ring for overvoltage protection
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Monitor
- TV

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.093g (approximately)

KEY PARAMETERS		
PARAMETER	**VALUE**	**UNIT**
I_F	2	A
V_{RRM}	20 - 40	V
I_{FSM}	80	A
$T_{J\ MAX}$	125	°C
Package	DO-214AA (SMB)	
Configuration	Single die	

Pb-Free RoHS COMPLIANT HALOGEN FREE

DO-214AA (SMB)

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)					
PARAMETER	**SYMBOL**	**SSL22**	**SSL23**	**SSL24**	**UNIT**
Marking code on the device		SL22	SL23	SL24	
Repetitive peak reverse voltage	V_{RRM}	20	30	40	V
Reverse voltage, total rms value	$V_{R(RMS)}$	14	21	28	V
Forward current	I_F	2			A
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	80			A
Junction temperature	T_J	- 55 to +125			°C
Storage temperature	T_{STG}	- 55 to +150			°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	70	°C/W
Junction-to-lead thermal resistance	$R_{\Theta JL}$	25	°C/W

ELECTRICAL SPECIFICATIONS (T_A = 25°C unless otherwise noted)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage(1)		I_F = 2A, T_J = 25°C	V_F	-	0.41	V
Reverse current @ rated V_R(2)		T_J = 25°C	I_R	-	400	μA
Reverse current @ rated V_R(2)	SSL22 SSL23	T_J = 100°C	I_R	-	50	mA
	SSL24			-	60	mA

Notes:

1. Pulse test with PW = 0.3ms
2. Pulse test with PW = 30ms

ORDERING INFORMATION

ORDERING CODE(1)	PACKAGE	PACKING
SSL2x	DO-214AA (SMB)	3,000 / Tape & Reel

Notes:

1. "x" defines voltage from 20V(SSL22) to 40V(SSL24)

CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

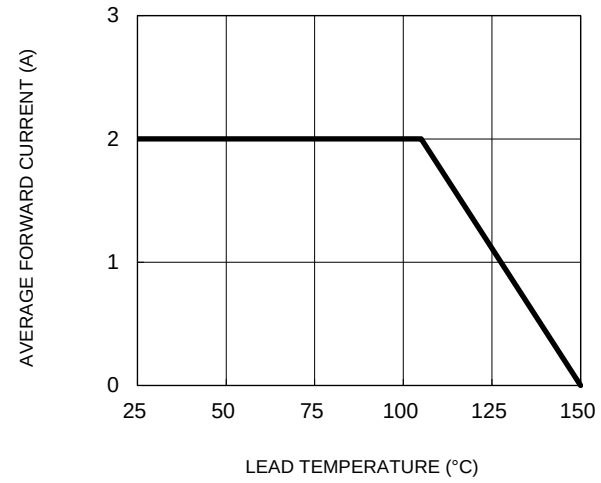


Fig.2 Typical Junction Capacitance

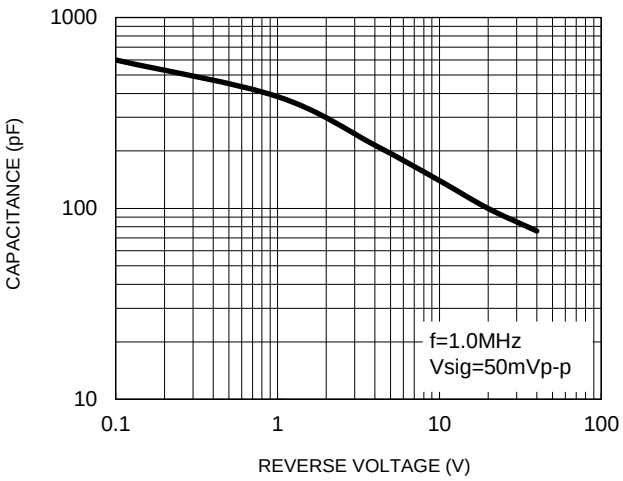


Fig.3 Typical Reverse Characteristics

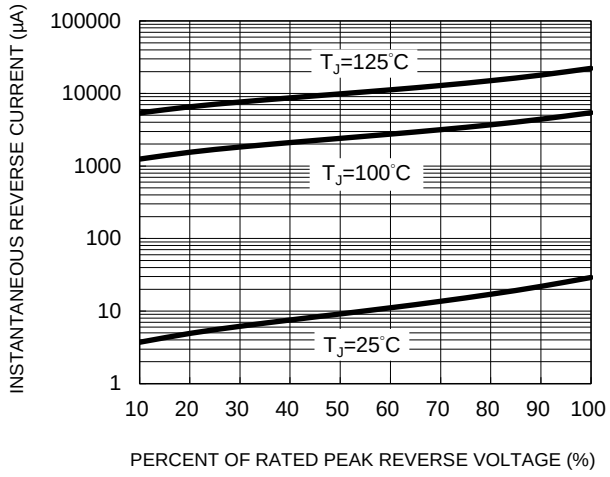


Fig.4 Typical Forward Characteristics

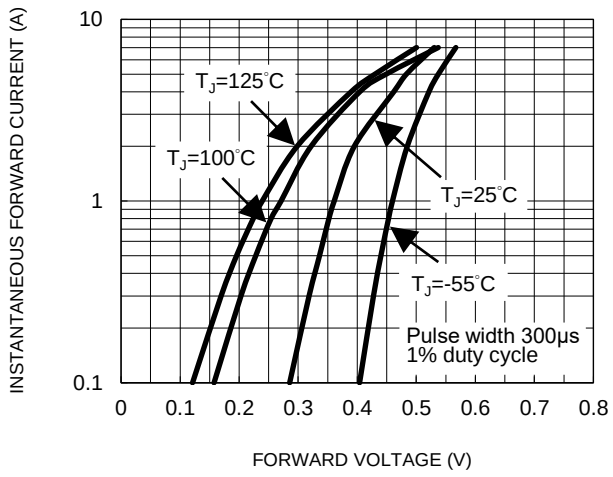
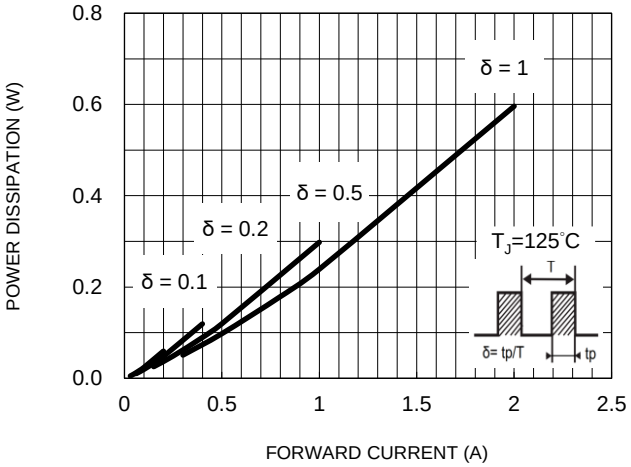


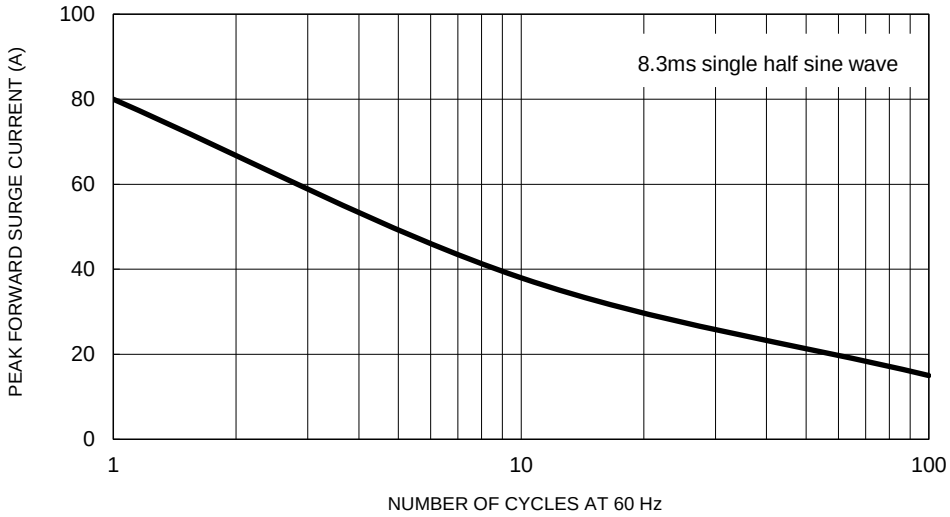
Fig.5 Typical Forward Power Dissipation vs. Forward Current



CHARACTERISTICS CURVES

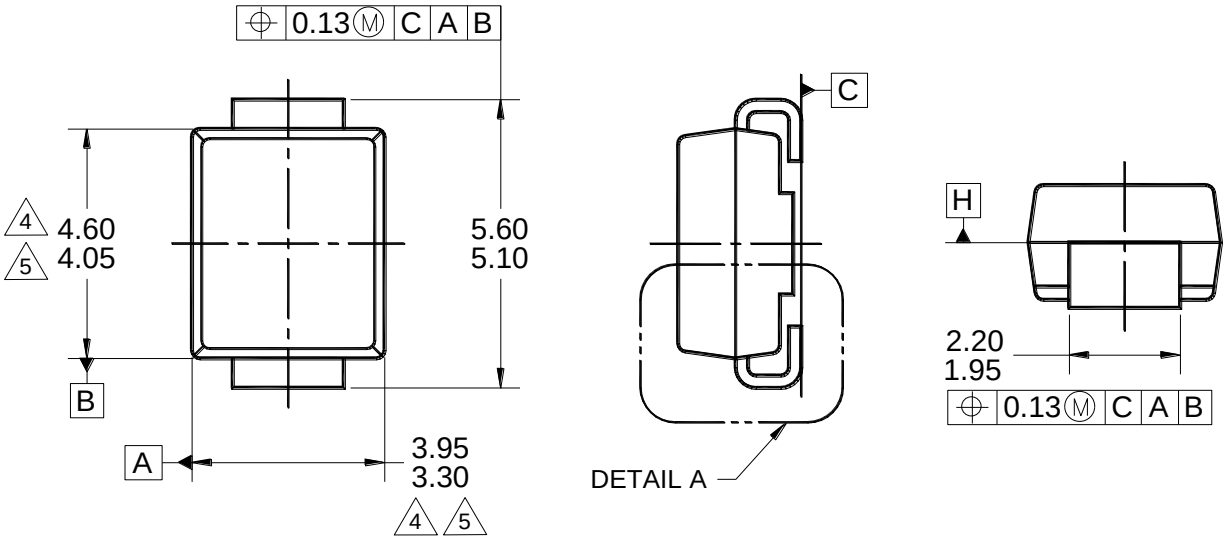
(T_A = 25°C unless otherwise noted)

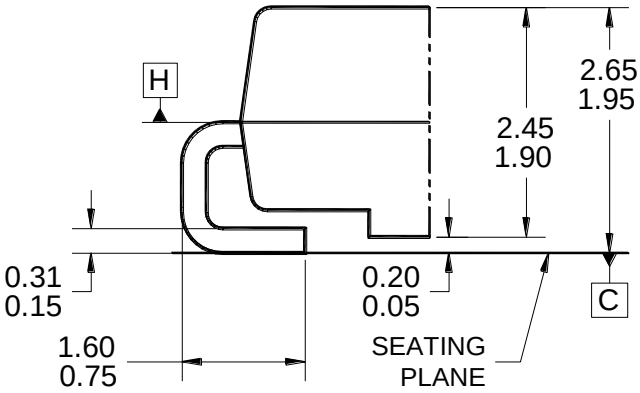
Fig.6 Maximum Non-Repetitive Forward Surge Current



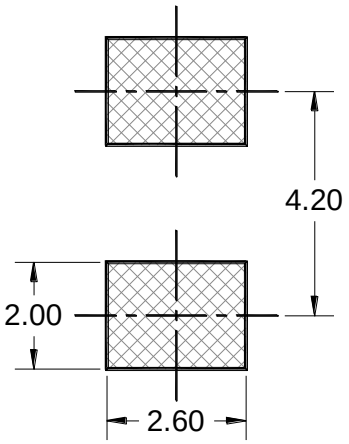
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)

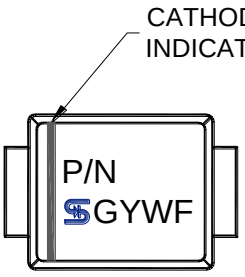




DETAIL A, ROTATED -90°
(SCALE 2:1)



SUGGESTED PAD LAYOUT



MARKING DIAGRAM

P/N = MARKING CODE
G = GREEN COMPOUND
YW = DATE CODE
F = FACTORY CODE

NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AA, ISSUE D.
4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
5. MOLDED PLASTIC BODY LATERAL DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.
6. DWG NO. REF: HQ2SD07-DO214SMB-035 REV A.

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